

PRODUCT CHANGE NOTICE

PCN-2635 REV1

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:	
10 August, 2023	10 November, 2023	Discrete	Clip Bond, Lead Frame, Mold Compound	2635	

TITLE

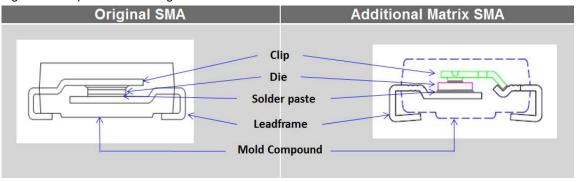
Qualification of Additional Clip Bonding, Lead Frame Structure (Matrix) and Mold Compound for Select Discrete Products

DESCRIPTION OF CHANGE

This PCN is being issued to notify customers that in order to assure continuity of supply and to improve assembly manufacturability, Diodes Incorporated has qualified additional clip bonding, lead frame structure (Matrix) and mold compound at Diodes subcontractor Eris Technology Corp. (ERIS) in Taiwan for select Discrete products.

Full electrical characterization and high reliability testing has been completed on representative part numbers to ensure no change to device functionality or electrical specifications in the datasheet. Refer to the attached qualification report embedded in this file (to view, download this PCN file then open it with a PDF viewer to see the attached qual report).

Figure 1: Comparison of Package Construction



There will be no change to the Form, Fit or Function of affected products.				
IMPACT				
No change in datasheet parameters				
PRODUCTS AFFECTED				
SMAZ5V1-13-F				
SMAZ5V6-13-F				
WEB LINKS				
Manufacturer's Notice:	https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/			
For More Information Contact:	https://www.diodes.com/about/contact-us/contact-sales/			
Data Sheet:	heet: https://www.diodes.com/catalog/			

Rel Date: 6/16/2021



DISCLAIMER

Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.

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